



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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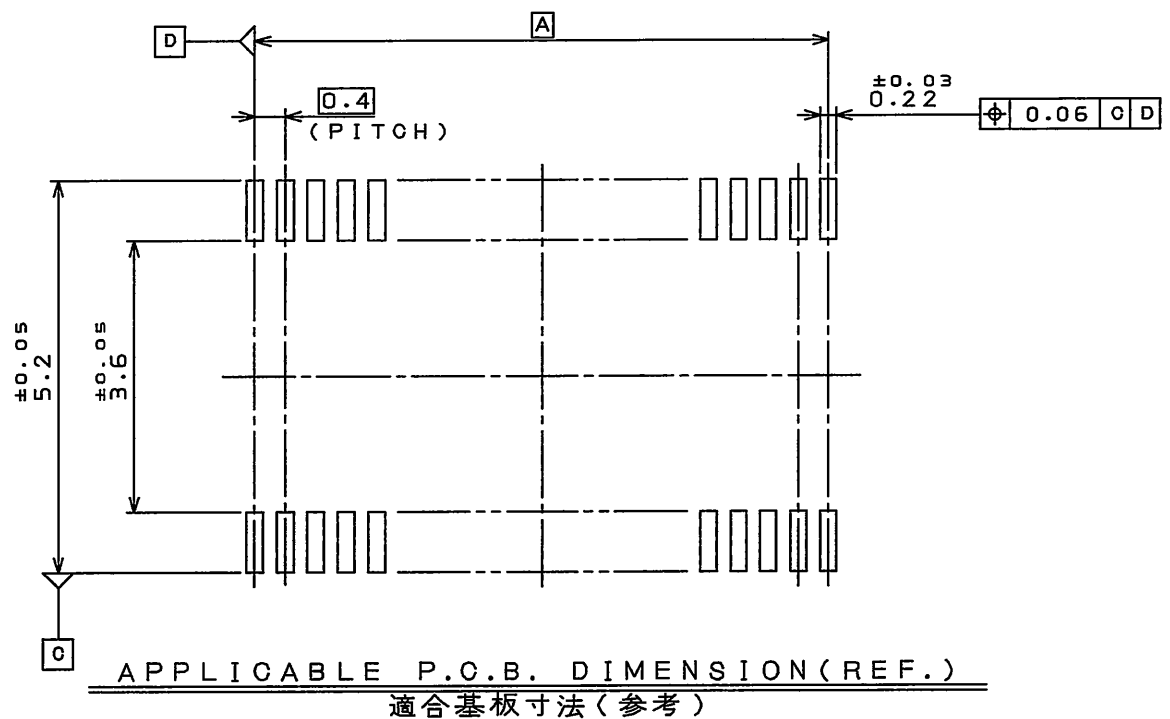
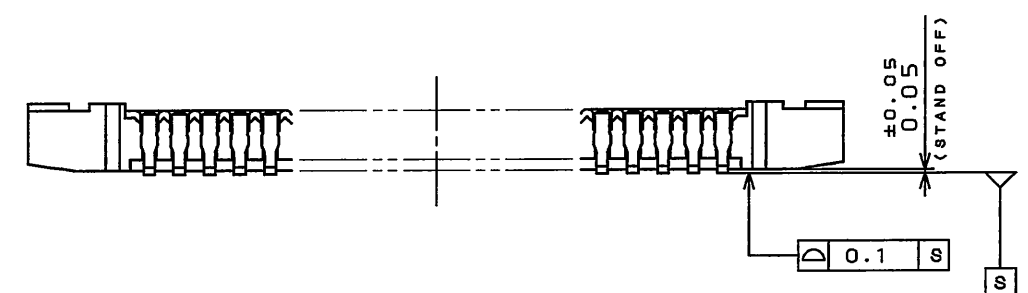
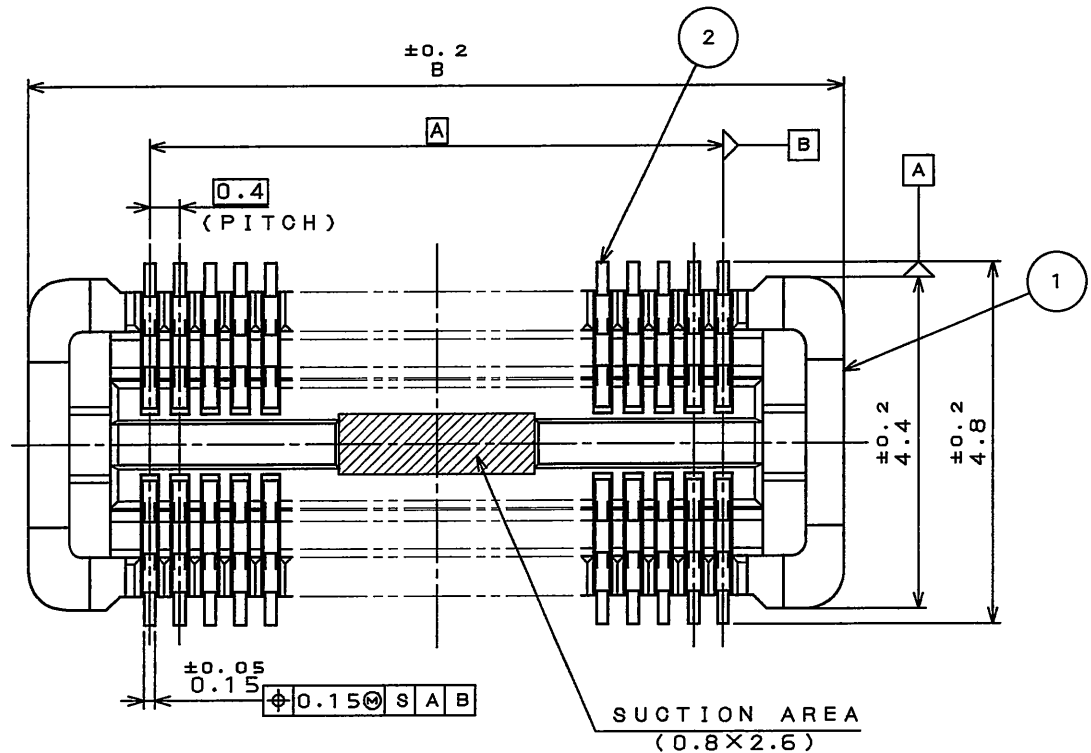
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LZ120171
(ON DRAWING NO.)

版数 REV.	年月日 DATE	DCN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
2	3.Mar.2006	059496	ADDED ITEM		H.OBIKANE	M.KIMURA	K.HISATOMI
3	5.Feb.2009	067369	ADDED ITEM		H.MATSUZAKI	H.OBIKANE	Y.YAHIRO
4	20.Oct.2009	068825	ADDED WORD		H.MATSUZAKI	H.OBIKANE	Y.YAHIRO
5	12.Jul.2010	070310	ADDED ITEM		H.MATSUZAKI	H. Oshino	T. Harada

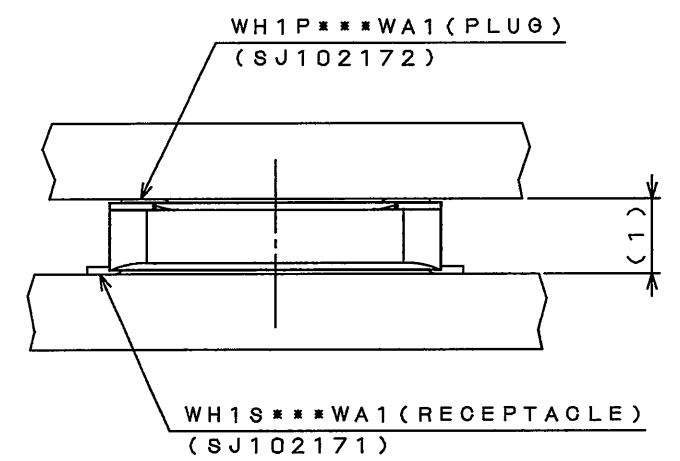
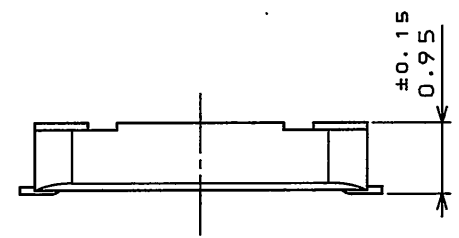


DESIGNATION

命名法
 WH1S***WA1
 SERIES シリーズ
 CONNECTOR FORM S:RECEPTACLE コネクタ形状 S:レセプタクル
 NUMBER OF CONTACTS 芯数
 MODIFY CODE モディファイコード
 CONTACT FINISH A:GOLD PLATING(0.1μm MIN) (CONTACT AREA) Δ
 コンタクト仕上げ A:金0.1μm以上 (接触部)
 W:SMT, STRAIGHT TYPE, WITHOUT HOLD DOWN
 W:SMT,ストレートタイプ,ホールドダウン無し

TABLE 1

名称 (TITLE)	A	B
WH1S024WA1	4.4	7.6
Δ WH1S030WA1	5.6	8.8
Δ WH1S040WA1	7.6	10.8
Δ WH1S050WA1	9.6	12.8
Δ WH1S060WA1	11.6	14.8



MATED CONDITION (REF.)
 嵌合状態図 (参考)

符号 NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	備考 REMARKS
2	CONTACT	N	COPPER ALLOY	CONTACT AREA GOLD PLATING(0.1μm MIN)	
1	INSULATOR	1	GLASS FILLED LCP		
仕様書 (SPECIFICATION)		第1版 (ORIGINAL DATE)		尺度 (SCALE)	シリーズ (SERIES)
JACS-10255-*		30.Aug.2005		10:1	WH1
公差 (GENERAL TOLERANCE)		製図 DR.		名称 (TITLE)	
. ±0.8		R.KATOU		WH1S***WA1 (RECEPTACLE)	
.X ±0.4		担当 CHK.			
.XX ±0.1		査閲 APPD.			
.XXX ±		承認 APPD.			
		K.HISATOMI		質量 (MASS)	
図面番号 (DRAWING NO.)					版数 (REV.)
SJ102171					5

DOF-0-212F(05.08)

